



ALPHA & OMEGA
SEMICONDUCTOR

AONS21357
30V P-Channel MOSFET

General Description

- Latest advanced trench technology
- Low $R_{DS(ON)}$
- High Current Capability
- RoHS and Halogen-Free Compliant

Product Summary

V_{DS}	-30V
I_D (at $V_{GS}=-10V$)	-36A
$R_{DS(ON)}$ (at $V_{GS}=-10V$)	< 7.8mΩ
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$)	< 12.3mΩ

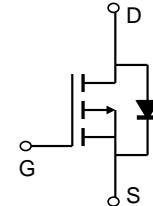
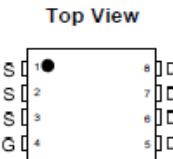
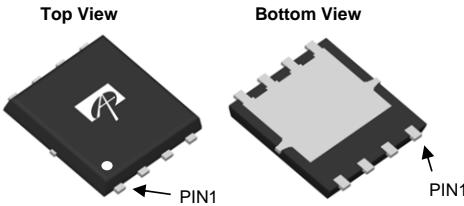
Applications

- Notebook AC-in load switch
- Battery protection charge/discharge

100% UIS Tested
100% R_g Tested



DFN5x6



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AONS21357	DFN 5x6	Tape & Reel	3000

Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 25	V
Continuous Drain Current ^G	I_D	-36	A
$T_C=100^\circ C$		-36	
Pulsed Drain Current ^C	I_{DM}	-144	
Continuous Drain Current	I_{DSM}	-21	A
$T_A=70^\circ C$		-17	
Avalanche Current ^C	I_{AS}	39	A
Avalanche energy $L=0.1mH$ ^C	E_{AS}	76	mJ
Power Dissipation ^B	P_D	48	W
$T_C=100^\circ C$		19	
Power Dissipation ^A	P_{DSM}	5.0	W
$T_A=70^\circ C$		3.2	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	20	25	°C/W
Maximum Junction-to-Ambient ^{A,D}		45	55	°C/W
Maximum Junction-to-Case	$R_{\theta JC}$	2.1	2.6	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}, V_{GS}=0\text{V}$	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-30\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			-1 -5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm25\text{V}$			±100	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.3	-1.7	-2.3	V
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}, I_D=-20\text{A}$ $T_J=125^\circ\text{C}$		6.3	7.8	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-20\text{A}$		9.8	12.3	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=-5\text{V}, I_D=-20\text{A}$		50		S
V_{SD}	Diode Forward Voltage	$I_S=-1\text{A}, V_{GS}=0\text{V}$		-0.7	-1	V
I_S	Maximum Body-Diode Continuous Current ^G				-36	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=-15\text{V}, f=1\text{MHz}$		2830		pF
C_{oss}	Output Capacitance			430		pF
C_{rss}	Reverse Transfer Capacitance			365		pF
R_g	Gate resistance	$f=1\text{MHz}$		14	28	Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, I_D=-20\text{A}$		50	70	nC
$Q_g(4.5\text{V})$	Total Gate Charge			25	35	nC
Q_{gs}	Gate Source Charge			9		nC
Q_{gd}	Gate Drain Charge			12		nC
$t_{D(\text{on})}$	Turn-On Delay Time	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, R_L=0.75\Omega, R_{\text{GEN}}=3\Omega$		12.5		ns
t_r	Turn-On Rise Time			18		ns
$t_{D(\text{off})}$	Turn-Off Delay Time			125		ns
t_f	Turn-Off Fall Time			66		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-20\text{A}, di/dt=500\text{A}/\mu\text{s}$		32		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-20\text{A}, di/dt=500\text{A}/\mu\text{s}$		62		nC

A. The value of $R_{\text{DS(on)}}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The Power dissipation $P_{\text{DS(on)}}$ is based on $R_{\text{DS(on)}} \leq 10\text{s}$ and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Single pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$.

D. The $R_{\text{DS(on)}}$ is the sum of the thermal impedance from junction to case R_{JJC} and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

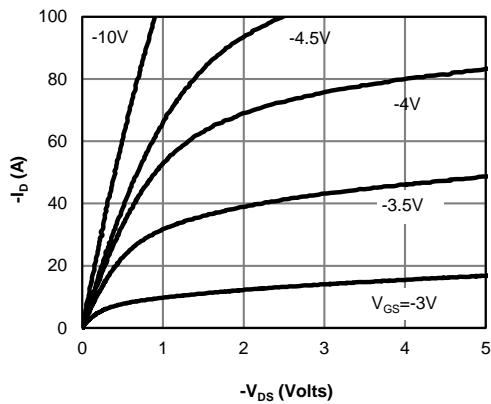
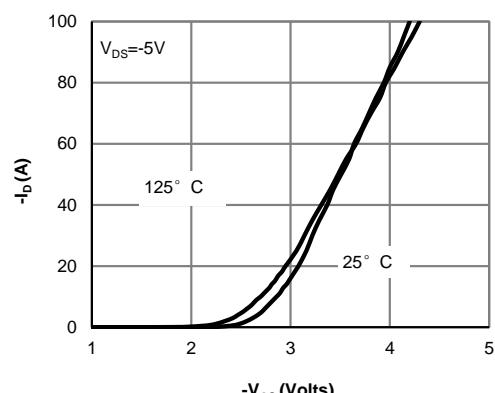
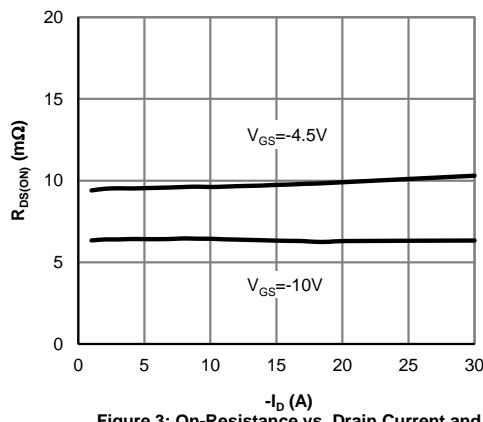
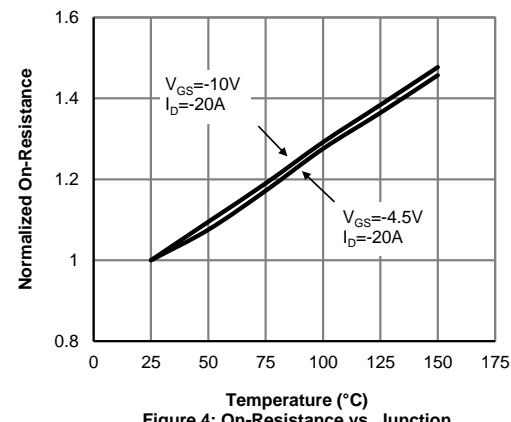
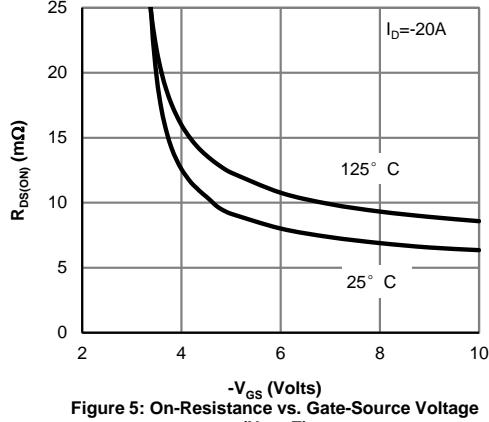
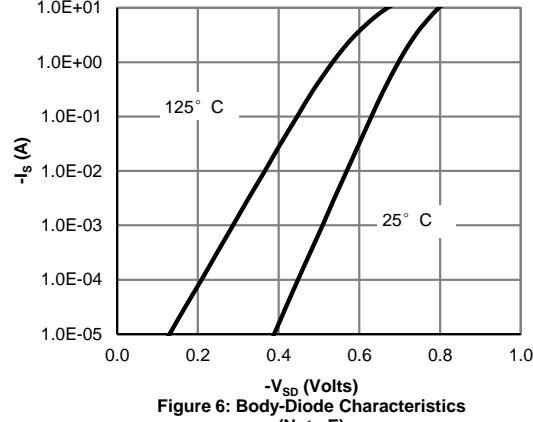
F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(\text{MAX})}=150^\circ\text{C}$. The SOA curve provides a single pulse rating.

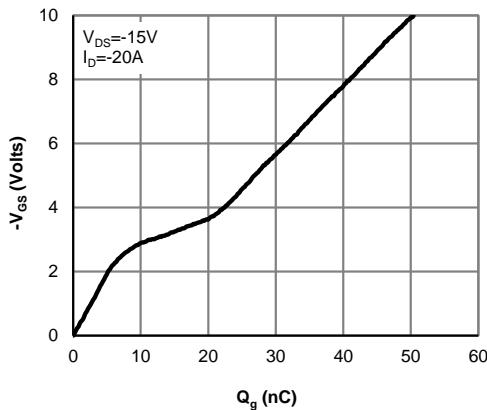
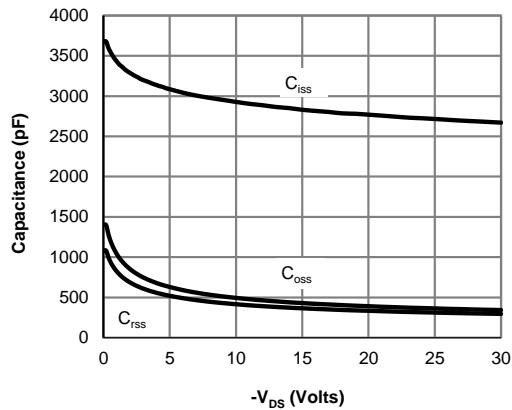
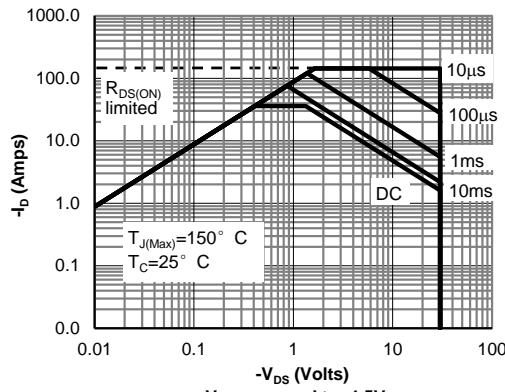
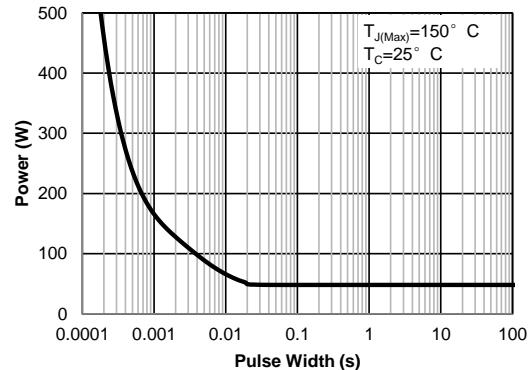
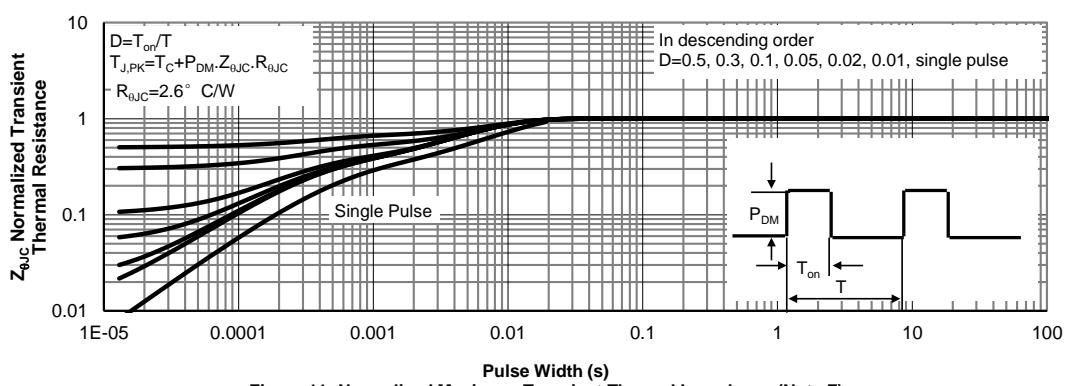
G. The maximum current rating is package limited.

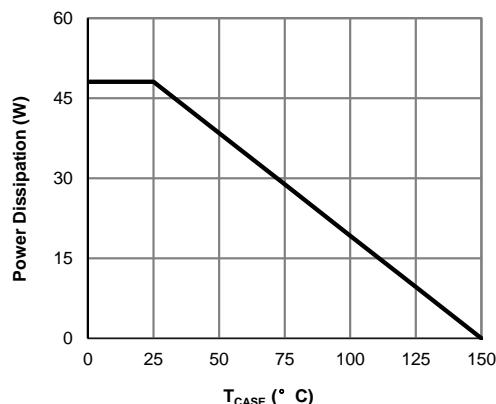
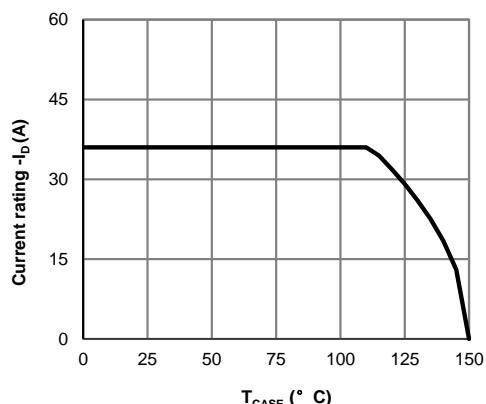
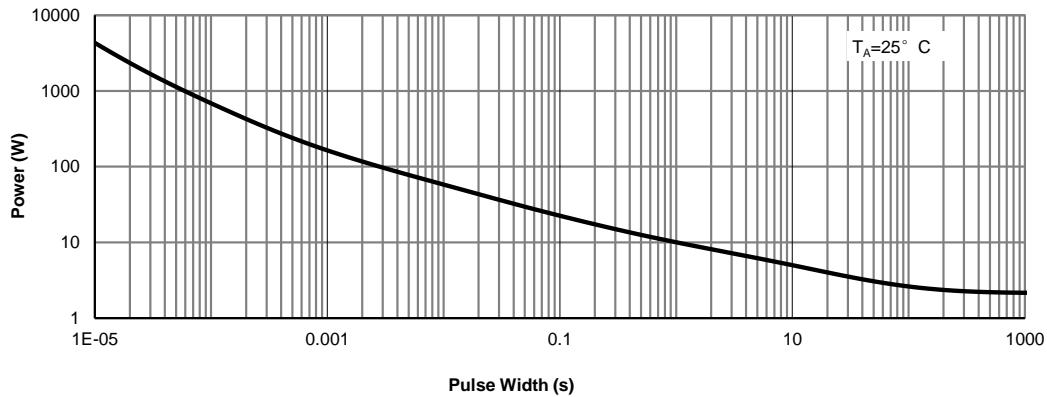
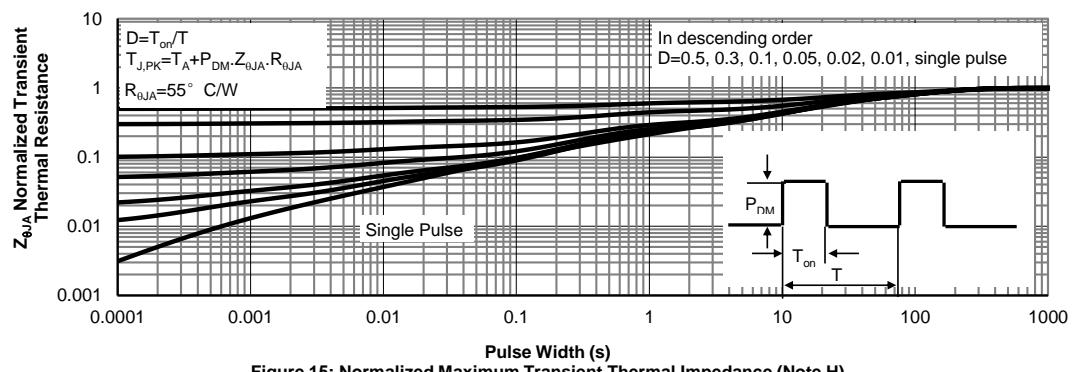
H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 1: On-Region Characteristics (Note E)

Figure 2: Transfer Characteristics (Note E)

Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

Figure 4: On-Resistance vs. Junction Temperature (Note E)

Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 12: Power De-rating (Note F)

Figure 13: Current De-rating (Note F)

Figure 14: Single Pulse Power Rating Junction-to-Ambient (Note H)

Figure 15: Normalized Maximum Transient Thermal Impedance (Note H)

